ABSTRACT

"Device and method for surface profilometry for control of wafers during processing"

The present invention relates to a device or apparatus for carrying out measurements of shape on a first surface (13) of a wafer (12) relative to structures (14) present beneath said first surface (13) comprising (i) profilometry means (10) arranged in order to carry out measurements of shape on said first surface (13) of the wafer (12) according to at least one measurement field; (ii) imaging means (11) facing said profilometry means (10) and arranged in order to acquire a reference image of said structures (14) on or through a second surface of the wafer (12) opposite to the first surface (13) according to at least one imaging field; said profilometry means (10) and said imaging means (11) being arranged so that the measurement and imaging fields are referenced in position within a common frame of reference (15).

The invention also relates to a method implemented in this device or this apparatus.

See Figure 1.